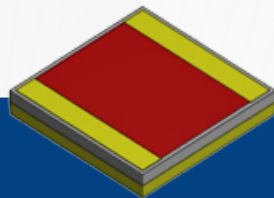


Overview

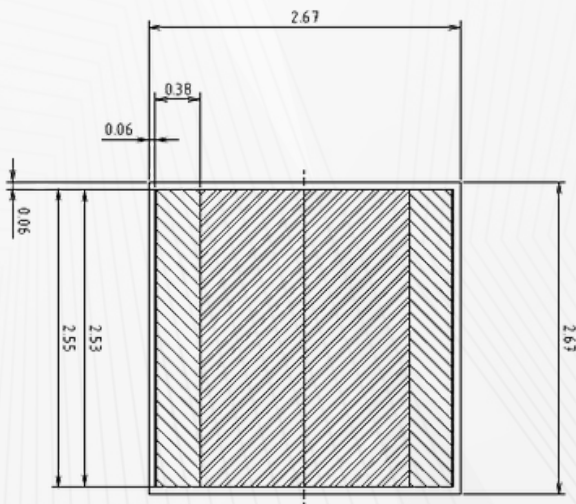
The devices are suitable for applications requiring high CW and peak powers, a broad frequency response, and small dimensions.

All thin-film products with pure Au contacts are suitable for soldering and wire bonding.

Typical product specifications



All sputtered coatings



Standard Designs

Type	RCVD20	RCVD50	RCVD80	RCVD125
#150-112-	1020-B	1019-B	1018-B	1017-B
Length ¹ (mm)	1.14	1.40	1.65	2.67
Width ¹ (mm)	0.63	1.40	0.89	2.67
Thickness ¹ (mm)	0.38	0.38	0.38	0.38
Power CW (W)	20	50	50	125
Capacitance ² (pF)	0.09	0.25	0.19	0.91
Cutoff frequency (DC – GHz)	30	18	18	18
Thermal resistance ² (K/W)	0.53	0.19	0.26	0.05

¹ dimensional accuracy ± 0.127 mm

² calculated DC capacitance and CW thermal resistance

Metallization setback from edge : minimally 0.06mm, Metallization thickness : $\pm 25\%$ for each layer
 Au-contact width 0.23mm (0.38mm for RCVD125), Au metallization suitable for wire bonding and most solder processes

Specifications

1. Electrical	Resistance	50 Ω $\pm 5\%$ or trimmed to specification
	Capacitance (low f)	0.09- 0.91 pF (see table)
	Input power	CW 20- 125 W (see table)
	Peak power	not tested
2. Thermal	Thermal Resistance	0.05-0.53 K/W (see table)
	Operating temperature	Tested up to 125 °C in CW
	Maximum	
	Temperature Coefficient of Resistance	-100 ppm/K
3. Marking	Optional	
4. Quality	Visual and mechanical inspection per 824W154	
5. Packaging	Waffle pack	